

REMARKS

The application has been carefully reviewed in light of the Office Action dated May 16, 2005. Claims 1 to 7 are in the application, with Claims 1 and 5 being independent. Claims 1 to 3 and 5 have been amended herein. Reconsideration and further examination are respectfully requested.

Claim 3 was rejected under 35 U.S.C. § 112, second paragraph. The rejection is respectfully traversed, and is submitted to have been obviated by the amendments made to Claims 1 and 3. Accordingly, Claim 3 is believed to be in condition for allowance. In this regard, Applicants note that Claim 3 was not subject to any art rejections.

Claims 1, 2, and 4 were rejected under 35 U.S.C. § 102(b) over U.S. Patent No. 6,099,604 (Sandhu). Claims 5 to 7 were rejected under 35 U.S.C. § 103(a) over U.S. Patent No. 6,109,738 (Miyata) in view of Sandhu. The rejections are respectfully traversed.

According to one feature of the invention as recited by Claims 1 and 5, the composition for forming a piezoelectric film contains a material selected from the group consisting of 1,8-diazabicyclo[5.4.0]-7-undecene, 1,5-diazabicyclo[4.3.0]non-5-ene, and 1,4-diazabicyclo[2.2.2]octane. By virtue of this feature, it is possible to stabilize the dispersoid obtained from the metallic compound, and thereby improve the characteristics of a piezoelectric element.

Sandhu is not seen to teach or suggest at least the above-discussed feature.

Sandhu discloses a slurry which may include 1,8-diazabicyclo[5.4.0]-7-undecene or 1,4-diazabicyclo[2.2.2]octane. However, this slurry is not a composition for

forming a piezoelectric film. Rather, the slurry is used in the chemical-mechanical polishing of a semiconductor wafer, with the foregoing materials acting as chelating agents. For example, as shown in Fig. 3 of Sandhu, a surface of a wafer 12 is polished with the slurry 140, which contains a chelating agent 150. See col. 8, line 52 to col. 9, line 11 of Sandhu.

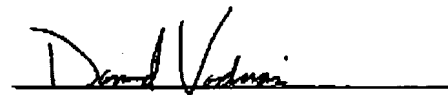
Miyata is not seen to remedy the deficiencies of Sandhu.

The dependent claims are also submitted to be patentable because they set forth additional aspects of the present invention and are dependent from the independent claims discussed above. Therefore, separate and individual consideration of each dependent claim is respectfully requested.

The application is believed to be in condition for allowance, and a Notice of Allowance is respectfully requested.

Applicants' undersigned attorney may be reached in our Costa Mesa, California office by telephone at (714) 540-8700. All correspondence should be directed to our address given below.

Respectfully submitted,



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